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ZXTP25012EZ

20V PNP high gain transistor in SOT89

Summary

$BV_{CEO} > -12V$

$h_{FE} > 500$

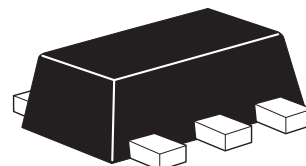
$I_{C(cont)} = 4.5A$

$V_{CE(sat)} < -70mV @ 1A$

$R_{CE(sat)} = 45m\Omega$

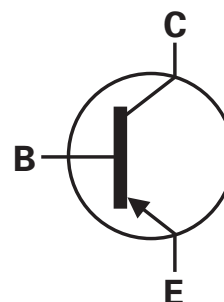
$P_D = 2.4W$

Complementary part number ZXTN25012EZ



Description

Packaged in the SOT89 outline this new low saturation 12V PNP transistor offers extremely low on state losses making it ideal for use in DC-DC circuits and various driving and power management functions.

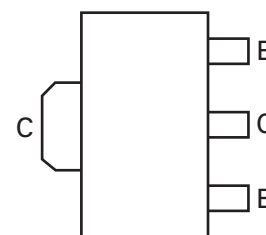


Features

- 4.5A continuous current
- Up to 10A peak current
- Very low saturation voltages
- High gain

Applications

- High side switch
- Battery charging
- Regulator circuits
- Buck converters
- MOSFET gate drivers



Pinout - top view

Ordering information

Device	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTP25012EZTA	7	12	1000

Device marking

- 1L4

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Absolute maximum ratings

Parameter	Symbol	Limit	Unit
Collector-Base voltage	V_{CBO}	-20	V
Collector-Emitter voltage	V_{CEO}	-12	V
Emitter-Base voltage	V_{EBO}	-7	V
Continuous Collector current ^(c)	I_C	-4.5	A
Base current	I_B	-1	A
Peak pulse current	I_{CM}	-10	A
Power dissipation at $T_A = 25^\circ\text{C}^{(a)}$	P_D	1.1	W
Linear derating factor		8.8	mW/°C
Power dissipation at $T_A = 25^\circ\text{C}^{(b)}$	P_D	1.8	W
Linear derating factor		14.4	mW/°C
Power dissipation at $T_A = 25^\circ\text{C}^{(c)}$	P_D	2.4	W
Linear derating factor		19.2	mW/°C
Power dissipation at $T_A = 25^\circ\text{C}^{(d)}$	P_D	4.46	W
Linear derating factor		35.7	mW/°C
Power dissipation at $T_A = 25^\circ\text{C}^{(d)}$	P_D	19.2	W
Linear derating factor		153	mW/°C
Operating and storage temperature range	T_j, T_{stg}	-55 to 150	°C

Thermal resistance

Parameter	Symbol	Limit	Unit
Junction to ambient ^(a)	$R_{\theta JA}$	117	°C/W
Junction to ambient ^(b)	$R_{\theta JA}$	68	°C/W
Junction to ambient ^(c)	$R_{\theta JA}$	51	°C/W
Junction to ambient ^(d)	$R_{\theta JA}$	28	°C/W
Junction to case ^(e)	$R_{\theta JC}$	7.95	°C/W

NOTES:

(a) For a device surface mounted on 15mm x 15mm x 0.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.

(b) Mounted on 25mm x 25mm x 0.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.

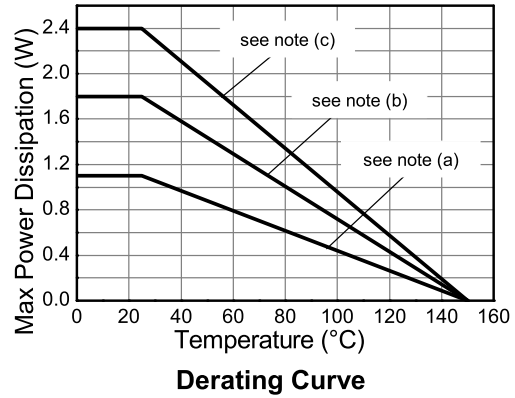
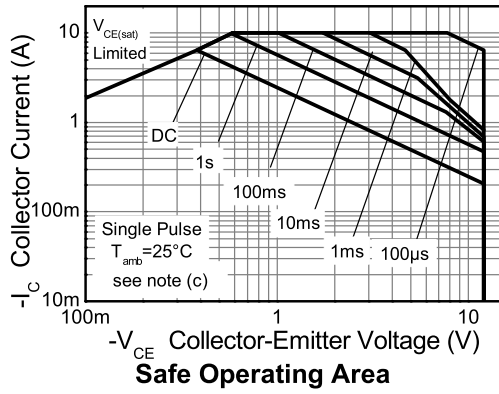
(c) Mounted on 50mm x 50mm x 0.6mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions.

(d) As (c) above measured at $t < 5$ seconds.

(e) Junction to case (collector tab). Typical

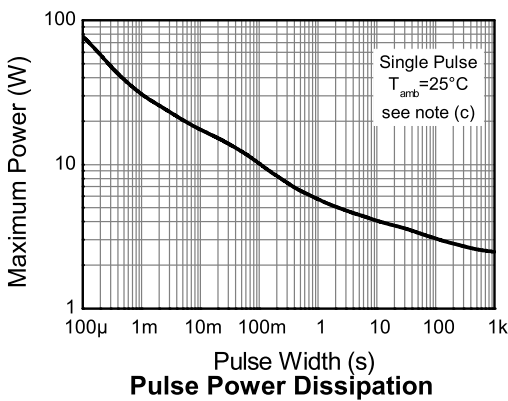
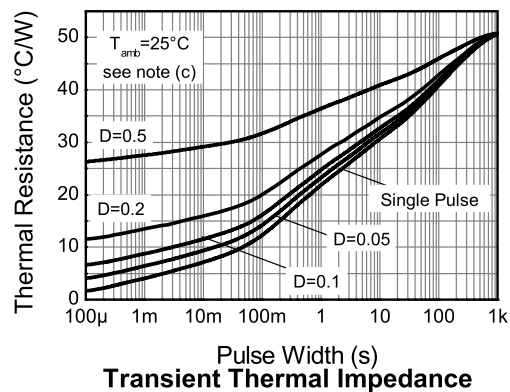
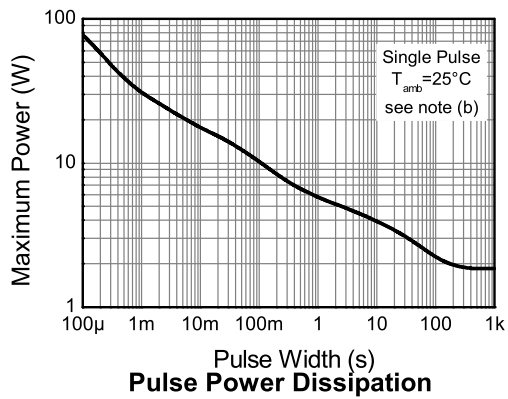
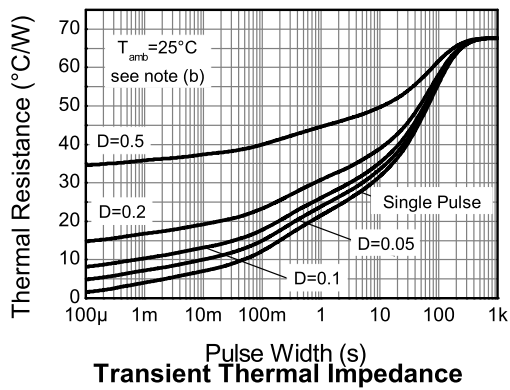
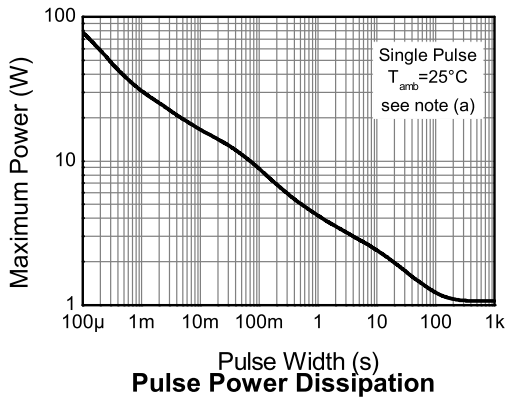
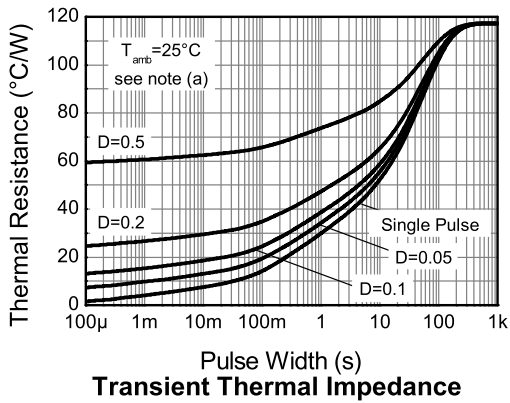
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Thermal characteristics



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Thermal characteristics



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Electrical characteristics (at $T_{amb} = 25^{\circ}\text{C}$ unless otherwise stated)

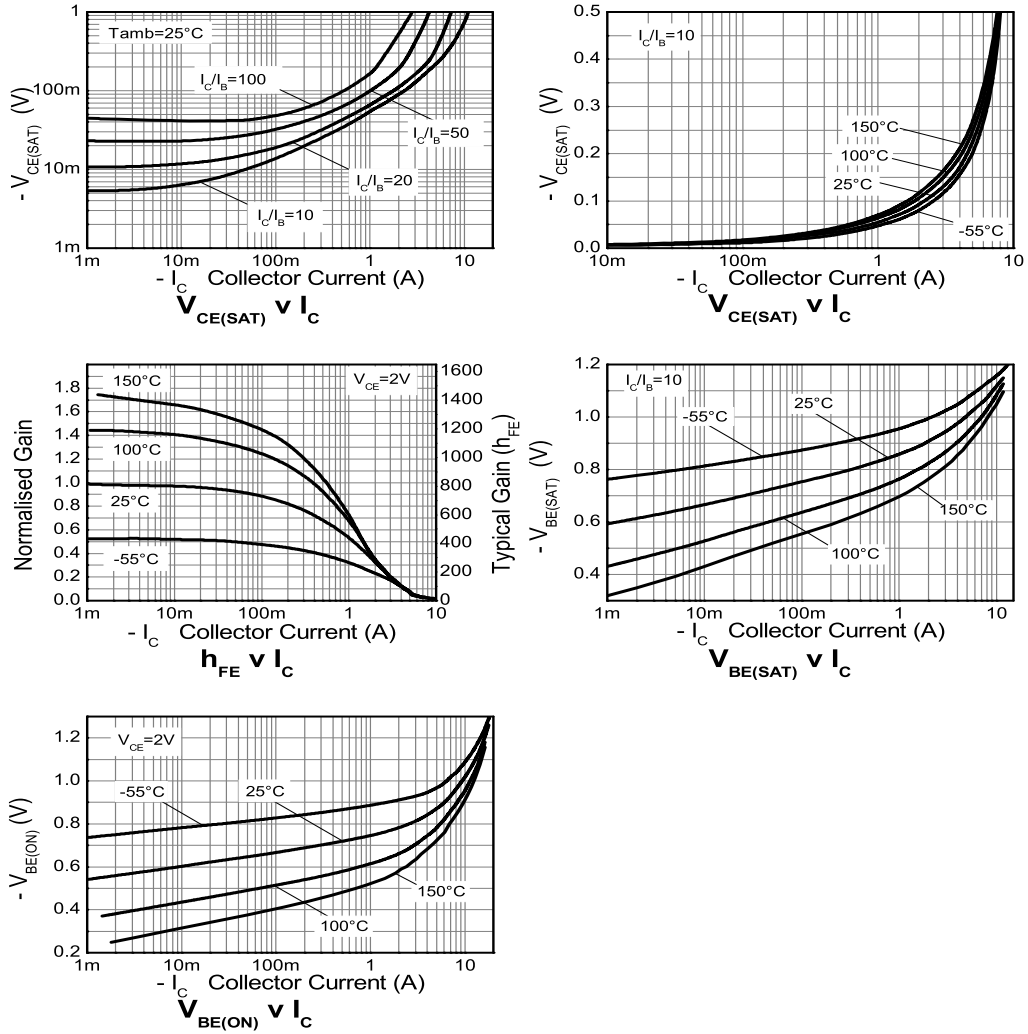
Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Collector-Base breakdown voltage	BV_{CBO}	-12	-35		V	$I_C = -100\mu\text{A}$
Collector-Emitter breakdown voltage	BV_{CEO}	-12	-25		V	$I_C = -10\text{mA}^{(*)}$
Emitter-Base breakdown voltage	BV_{EBO}	-7	-8.5		V	$I_E = -100\mu\text{A}$
Collector-Base cut-off current	I_{CBO}		<-1	-50 -0.5	nA μA	$V_{CB} = -12\text{V}$ $V_{CB} = -12\text{V}, T_{amb} = 100^{\circ}\text{C}$
Emitter Base cut-off current	I_{EBO}		<-1	-50	nA	$V_{EB} = -5.6\text{V}$
Collector-Emitter saturation voltage	$V_{CE(sat)}$		-55 -155 -185 -200	-70 -265 -355 -285	mV mV mV mV	$I_C = -1\text{A}, I_B = -100\text{mA}^{(*)}$ $I_C = -1\text{A}, I_B = -10\text{mA}^{(*)}$ $I_C = -2\text{A}, I_B = -40\text{mA}^{(*)}$ $I_C = -4.5\text{A}, I_B = -450\text{mA}^{(*)}$
Base-Emitter saturation voltage	$V_{BE(sat)}$		-990	-1100	mV	$I_C = -4.5\text{A}, I_B = -450\text{mA}^{(*)}$
Base-Emitter turn-on voltage	$V_{BE(on)}$		-865	-975	mV	$I_C = -4.5\text{A}, V_{CE} = -2\text{V}^{(*)}$
Static forward current transfer ratio	h_{FE}	500 300 40	800 450 85 15	1500		$I_C = -10\text{mA}, V_{CE} = -2\text{V}^{(*)}$ $I_C = -1\text{A}, V_{CE} = -2\text{V}^{(*)}$ $I_C = -4.5\text{A}, V_{CE} = -2\text{V}^{(*)}$ $I_C = -10\text{A}, V_{CE} = -2\text{V}^{(*)}$
Transition frequency	f_T		310		MHz	$I_C = -50\text{mA}, V_{CE} = -10\text{V}$ $f = 100\text{MHz}$
Input capacitance	C_{ibo}		127	250	pF	$V_{EB} = -0.5\text{V}, f = 1\text{MHz}^{(*)}$
Output capacitance	C_{obo}		16.9	30	pF	$V_{CB} = -10\text{V}, f = 1\text{MHz}^{(*)}$
Delay time	t_d		41		ns	$V_{CC} = -10\text{V}, I_C = -1\text{A},$ $I_{B1} = -I_{B2} = -10\text{mA}$
Rise time	t_r		62		ns	
Storage time	t_s		179		ns	
Fall time	t_f		65		ns	

NOTES:

 (*) Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.

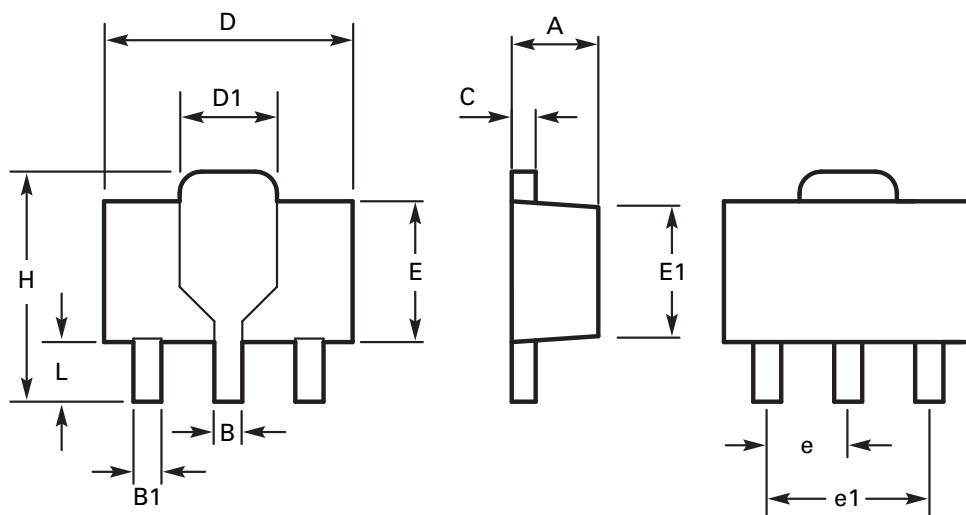
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Typical characteristics



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Package outline



DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min	Max	Min	Max		Min	Max	Min	Max
A	1.40	1.60	0.550	0.630	E	2.29	2.60	0.090	0.102
B	0.44	0.56	0.017	0.022	E1	2.13	2.29	0.084	0.090
B1	0.36	0.48	0.014	0.019	e	1.50 BSC		0.059 BSC	
C	0.35	0.44	0.014	0.017	e1	3.00 BSC		0.118 BSC	
D	4.40	4.60	0.173	0.181	H	3.94	4.25	0.155	0.167
D1	1.52	1.83	0.064	0.072	L	0.89	1.20	0.035	0.047

Note: Controlling dimensions are in millimeters. Approximate dimensions are provided in inches

ZXTP25012EZ

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